Amendments to the Claims:

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) An array for producing a Micro Electro Mechanical System (MEMS) device comprising:

various types of circuit elements including a plurality of circuit elements of each type, and

switches for connecting each of said circuit elements, wherein

~~at least one of said switches are connected on each side of said circuit elements,~~

said circuit elements are arranged in rows and columns,

an input terminal and an output terminal of each circuit element have respectively a switch connecting an adjacent circuit element on a row in series and a switch connecting an adjacent circuit element on a column in parallel, and

some of said circuit elements are interconnected by determining open or close of all of said switches so as to make a circuit.

2. (Previously Presented) An array for producing a MEMS device as set forth in claim 1, wherein the switches connecting the circuit elements are semiconductor switches.

3. (Withdrawn) A MEMS array as set forth in claim 1, wherein the switches connecting the elements are mechanical switches.

4. (Previously Presented) An array for producing a MEMS device as set forth in claim 1, provided with an interconnect layer, said substrate being formed with said switches, said interconnect layer provided with a plurality of circuit elements connected through said switches.

5. (Previously Presented) An array for producing a MEMS device as set forth in claim 4, wherein said substrate is provided with drive parts for driving said switches.

6. (Previously Presented) An array for producing a MEMS device as set forth in claim 5, wherein said substrate is further provided with semiconductor circuits for signal processing.

7. (Previously Presented) An array for producing a MEMS device as set forth in claim 6, wherein said semiconductor circuits have three-dimensional structures.

8-11. (Canceled)

12. (Withdrawn) A MEMS array as set forth in claim 1, provided with a substrate and interconnect layer, said interconnect layer provided with a plurality of elements, switches for connecting said elements being provided on the interconnect layer.

13. (Withdrawn) A MEMS array as set forth in claim 12, wherein said substrate is provided with drive parts for driving said switches.

14. (Withdrawn) A MEMS array as set forth in claim 13, wherein said substrate is provided with semiconductor circuits for signal processing.

15. (Withdrawn) A MEMS array as set forth in claim 14, wherein said semiconductor circuits have three-dimensional structures.

16. (Previously Presented) An array for producing a MEMS device as set forth in claim 1, wherein the same package packages semiconductor circuits built therein.

17. (Withdrawn) A method of production of a MEMS array providing an interconnect layer on a substrate, said method of production of a MEMS array characterized by having: a step of forming a plurality of switches in said substrate and a step of forming pluralities of various types of elements for each type connected through said plurality of switches in said interconnect layer.

18. (Withdrawn) A method of production of a MEMS array providing an interconnect layer on a substrate, said method of production of a MEMS array characterized by having: a step of forming pluralities of various types of elements for each type in said interconnect layer and a step of providing a plurality of switches for connecting said elements on said interconnect layer.

19. (Withdrawn) A method of production of a MEMS array providing an interconnect layer on a substrate, said method of production of a MEMS array characterized by having: a step of forming switch drive parts on said substrate, a step of forming pluralities of various types of elements for each type in said interconnect layer, and a step of providing a plurality of switches for connecting said elements on said interconnect layer.

20. (Withdrawn) A method of production of a MEMS device having a plurality of elements of the same arrangement as a MEMS array provided with a plurality of elements and switches for connecting said elements, said method of production of a MEMS device characterized by having: a step of determining connection states of switches of said MEMS array and a step of forming an interconnect layer connecting elements in accordance with the connection states of said switches.

21. (Withdrawn) A method of production of a MEMS device having a plurality of elements of the same arrangement as a MEMS array provided with a plurality of elements and switches for connecting said elements, said method of production of a MEMS device characterized by having: a step of determining connection states of switches of said MEMS array, a step of forming an interconnect layer connecting elements in accordance with the connection states of said switches on the substrate of said MEMS device, and a step of forming a plurality of elements of the same arrangement as the MEMS array on said interconnect layer.

22. (Withdrawn) A method of production of a MEMS device having a plurality of elements of the same arrangement as a MEMS array provided with a plurality of elements and switches for connecting said elements, said method of production of a MEMS device characterized by having: a step of determining connection states of switches of said MEMS array, a step of providing switches in the substrate of the MEMS device, a step of providing an additional interconnect layer for short-circuiting, opening, or connecting said switches in accordance with the connection states of said switches on the substrate of the MEMS device, and a step of providing an interconnect layer arranging a plurality of elements of the same arrangement as said MEMS array on said additional interconnect layer.

23. (Withdrawn) A method of production of a MEMS device having a plurality of elements of the same arrangement as a MEMS array provided with a plurality of elements and switches for connecting said elements, said method of production of a MEMS device characterized by having: a step of determining connection states of switches of said MEMS array, a step of forming an interconnect layer providing a plurality of elements of the same arrangement as said MEMS array, and a step of selectively forming switches and interconnects on said interconnect layer based on the connection states of said switches.

24. (New) An array for producing a MEMS device as set forth in claim 1, wherein the circuit elements are formed by utilizing the semiconductor wafer process.

25. (New) An array for producing a MEMS device as set forth in claim 24, wherein the circuit elements are passive circuit elements.